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3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
 - 3.1.1 Flip chip
 - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
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